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BSS123

N-Channel Logic Level Enhancement Mode Field Effect Transistor

General Description

These N-Channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance.These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

Features

- 0.17 A, 100 V. $R_{DS(ON)} = 6\Omega @ V_{GS} = 10$ V

  $R_{DS(ON)} = 10\Omega @ V_{GS} = 4.5$ V

- High density cell design for extremely low $R_{DS(ON)}$

- Rugged and Reliable

- Compact industry standard SOT-23 surface mount package

D

S

G

SOT-23

D

G   S
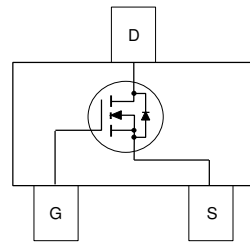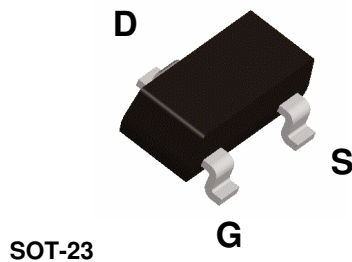
Absolute Maximum Ratings $T_A=25^oC$ unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		100	V
V_{GSS}	Gate-Source Voltage		±20	V
I_D	Drain Current – Continuous	(Note 1)	0.17	A
	– Pulsed		0.68	
P_D	Maximum Power Dissipation	(Note 1)	0.36	W
	Derate Above 25°C		2.8	mW/°C
T_J, T_{STG}	Operating and Storage Junction Temperature Range		−55 to +150	°C
T_L	Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds		300	

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1)	350	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
SA	BSS123	7"	8mm	3000 units

Electrical Characteristics

T_A = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV$_{DSS}$	Drain–Source Breakdown Voltage	V_{GS} = 0 V, I_D = 250 μA	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C		97		mV/°C
I$_{DSS}$	Zero Gate Voltage Drain Current	V_{DS} = 100 V, V_{GS} = 0 V			1	μA
		V_{DS} = 100 V, V_{GS} = 0 V T_J = 125°C			60	μA
		V_{DS} = 20 V, V_{GS} = 0 V			10	nA
I$_{GSS}$	Gate–Body Leakage.	V_{GS} = ±20 V, V_{DS} = 0 V			±50	nA
On Characteristics (Note 2)						
V$_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 1 mA	0.8	1.7	2	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = 1 mA, Referenced to 25°C		–2.7		mV/°C
R$_{DS(on)}$	Static Drain–Source On–Resistance	V_{GS} = 10 V, I_D = 0.17 A V_{GS} = 4.5 V, I_D = 0.17 A V_{GS} = 10 V, I_D = 0.17 A, T_J = 125°C		1.2 1.3 2.2	6 10 12	Ω
I$_{D(on)}$	On–State Drain Current	V_{GS} = 10 V, V_{DS} = 5 V	0.68			A
g$_{FS}$	Forward Transconductance	V_{DS} = 10V, I_D = 0.17 A	0.08	0.8		S
Dynamic Characteristics						
C$_{iss}$	Input Capacitance	V_{DS} = 25 V, V_{GS} = 0 V, f = 1.0 MHz		73		pF
C$_{oss}$	Output Capacitance			7		pF
C$_{rss}$	Reverse Transfer Capacitance			3.4		pF
R$_G$	Gate Resistance	V_{GS} = 15 mV, f = 1.0 MHz		2.2		Ω
Switching Characteristics (Note 2)						
t$_{d(on)}$	Turn–On Delay Time	V_{DD} = 30 V, I_D = 0.28 A, V_{GS} = 10 V, R_{GEN} = 6 Ω		1.7	3.4	ns
t$_r$	Turn–On Rise Time			9	18	ns
t$_{d(off)}$	Turn–Off Delay Time			17	31	ns
t$_f$	Turn–Off Fall Time			2.4	5	ns
Q$_g$	Total Gate Charge	V_{DS} = 30 V, I_D = 0.22 A, V_{GS} = 10 V		1.8	2.5	nC
Q$_{gs}$	Gate–Source Charge			0.2		nC
Q$_{gd}$	Gate–Drain Charge			0.3		nC
Drain–Source Diode Characteristics and Maximum Ratings						
I$_S$	Maximum Continuous Drain–Source Diode Forward Current				0.17	A
V$_{SD}$	Drain–Source Diode Forward Voltage	V_{GS} = 0 V, I_S = 0.34 A(Note 2)		0.8	1.3	V
t$_{rr}$	Diode Reverse Recovery Time	I_F = 0.17 A, di_F/d_t = 100 A/μs		11		nS
Q$_{rr}$	Diode Reverse Recovery Charge			3		nC

NOTE:

1. R$_{θJA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R$_{θJC}$ is guaranteed by design while R$_{θCA}$ is determined by the user's board design.

   a) 350°C/W when mounted on a minimum pad..

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%
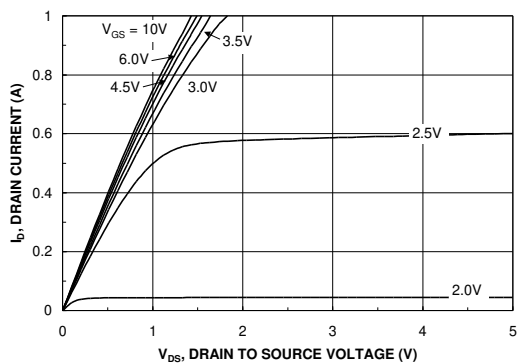
Typical Characteristics
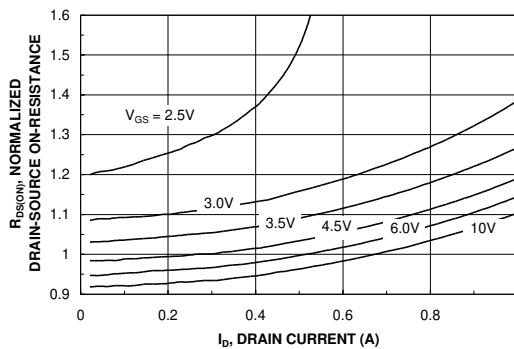
Figure 1. On-Region Characteristics.

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.
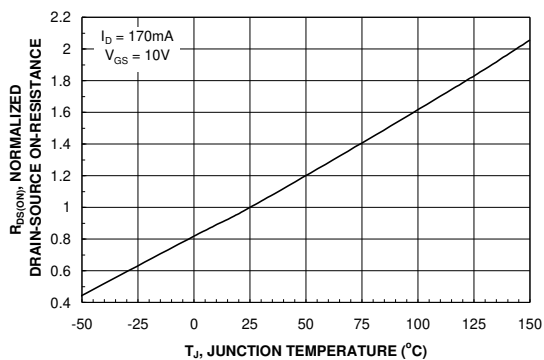
Figure 3. On-Resistance Variation with Temperature.
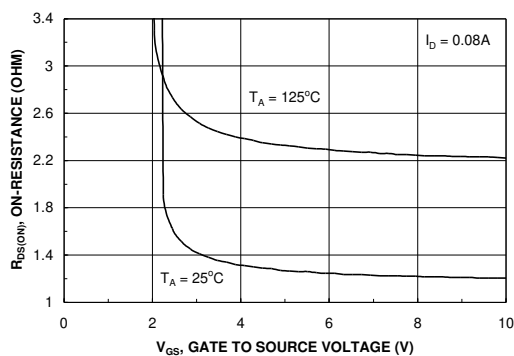
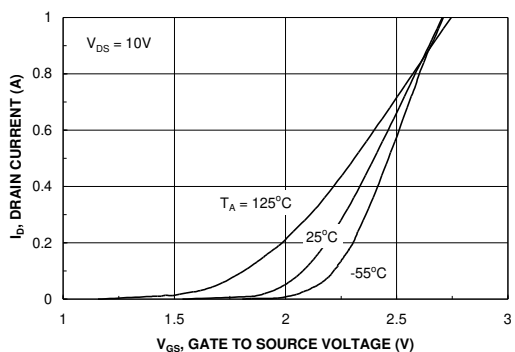**Figure 4. On-Resistance Variation with Gate-to-Source Voltage.**
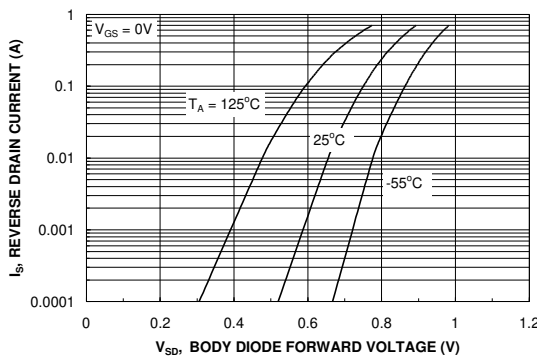
Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.
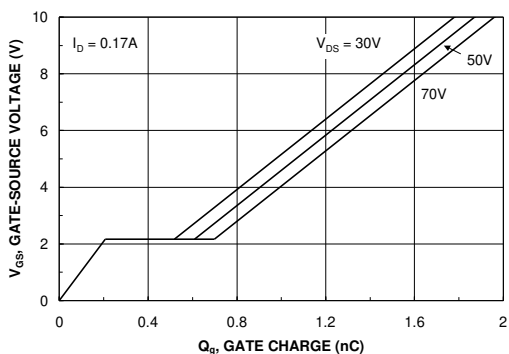
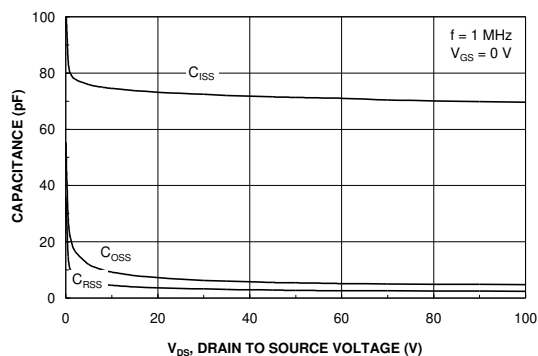## Typical Characteristics

Figure 7. Gate Charge Characteristics.

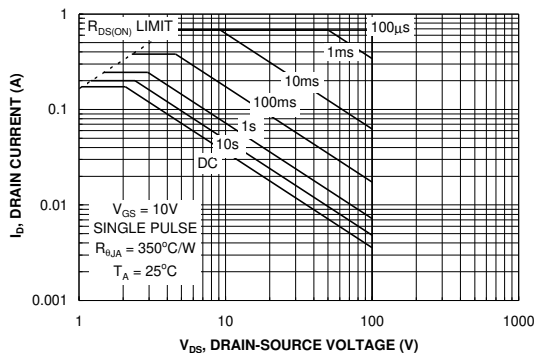

Figure 8. Capacitance Characteristics.
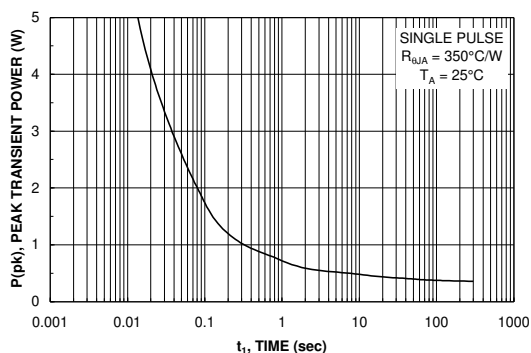

Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum
Power Dissipation.

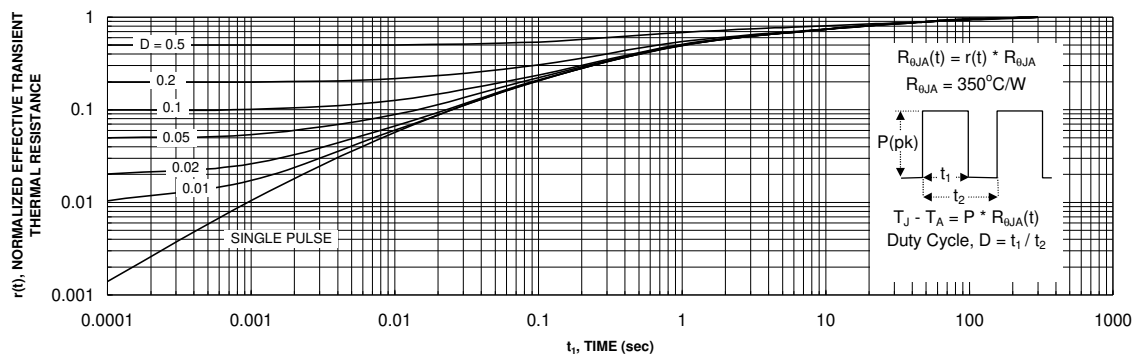$$R_{\theta JA}(t) = r(t) * R_{\theta JA}$$

$$R_{\theta JA} = 350°C/W$$

$$T_J - T_A = P * R_{\theta JA}(t)$$

Duty Cycle, $D = t_1 / t_2$

Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1a.
Transient thermal response will change depending on the circuit board design.

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Programmable Active Droop™		OPTOPLANAR™	SMART START™	

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